

From Lab to Market: CEA-Leti Innovation Days Leads the Way

June 23-25, 2026 | Grenoble, France

At the heart of the global semiconductor ecosystem

Once again, the global semiconductor industry turns its attention to this signature CEA-Leti event. For three dynamic days in Grenoble, [LID World Summit 2026](#) charts the pathway to sustainable breakthroughs powering the next wave of AI factories.

Attendees will have a front-row look at the materials and technologies enabling tomorrow's devices, systems, and markets—alongside the groundbreaking innovations driving progress across the health care, automotive, industrial, defense, and consumer electronics sectors.

The summit unites industry leaders, visionary startups, and technology pioneers from Europe, the US, and Asia. It is the premier venue to connect directly with the CEOs, CTOs, and decision-makers shaping the future of microelectronics and to discover the smart systems defining the next generation of technology.

160+ Industry Leaders & Technology Innovators

- Sébastien Dauvé (CEA-Leti)
- Tim Breen (GlobalFoundries)
- Thomas Rueckes (FMC)
- Audrey Charles (Lam Capital)
- Takaki Murata (Murata)
- Agnieszka Thonet (HP)
- Chih-I-Wu (ITRI)
- Hajime Shoji (Sumitomo Electric Industries)
- Dr. Atsuyoshi Koike (Rapidus)
- Bill Chang (Density AI)
- Laurent Rémond (SOITEC)
- Elliot Mc Namera (ASML)
- Sylvie Gellida (STMicroelectronics)
- Juan Rey (Siemens)
- Stuart Knight (HORIBA)
- Mark Fuselier (AMD)
- Takahiro Ogura (Preferred Networks)
- John Neuffer (SIA)
- Michael Schaffert (Bosch)
- Nathalie Feyt (Schneider Electric)
- Jean-René Lèquepeys (CEA-Leti)
- ... and many more global, industry influencers.

11 In-Depth Conferences

Presenting the latest in critical semiconductor advances and visions of the future

June 23: Plenary session

- [Lab to Market with Sustainable Chips to Power the Next Wave of AI Factories](#)

June 24: 6 conferences

- [Data & Network/Cloud Convergence](#)
- [Semiconductors for Computing](#)
- [Semiconductors for Defense](#)
- [Cybersecurity](#)
- [The FAMES Pilot Line](#)
- [The RESOLVE Initiative](#)

June 25: 4 conferences

- [Startups & Investments](#)
- [Tech Talks: Shaping What's Next](#)
- [Optical Interconnects](#)
- [Disruptive Digital Interfaces + closing talks by special guest](#)

Extensive Exhibitor Showcase, From Lab to Market: The Latest Breakthroughs and Real-World Applications

Innovation In Action: Explore 30+ Live Demos Driving the Future of Semiconductors

From Smart Health to High-Performance Silicon — Featuring Real-Time Breakthroughs:

One Health Technologies

Expanding multidisciplinary expertise and continuous innovation are essential to meet the healthcare sector's growing need for new technologies that prevent, predict, and treat diseases.

Latest Silicon Breakthroughs

When it comes to sensing, power electronics, memories or high-performance computing, silicon still offers superior performance. Discover the expertise of our platforms through different next-generation demonstrators.

Smart Systems Solutions

Smart technology will take products to the next level, improving user experiences and meeting expectations for Industry 4.0, cybersecurity, telecommunications and domestic applications.

Startups Corner: 14 Innovators Pushing the Boundaries of What's Possible

Meet the disruptors delivering tomorrow's tech

- [Nellow](#)
- [Moon Photonics](#)
- [NcodiN](#)
- [Quobly](#)
- [Scintil Photonics](#)
- [nawu diagnostics](#)
- [Injectpower](#)
- [Magellan by CEA](#)
- [Steerlight](#)
- [Wise Integration](#)
- [iNGage](#)
- [Entropie](#)
- [Amylen](#)
- [Oscala Biosciences](#)

Partners Corner: Engage with 34 Industry Leaders Driving Semiconductor Excellence

Proving the essential contributions of European collaborations

- [Semiconductor Production Systems](#)
- [SERMA Group](#)
- [PEPR Electronique](#)
- [The Carnot Network](#)
- [FMC](#)
- [EURIS](#)
- [MICROTEST](#)
- [SET](#)
- [T-Micro](#)
- [Technic](#)
- [Weebit Nano](#)
- [TDK Electronics](#)
- [Microworld](#)
- [KELTEN](#)
- [BBM Groupe](#)
- [BM&A](#)
- [Supernova Invest](#)
- [Ardian](#)
- [Agileo Automation](#)
- [EV Group](#)
- [SUSS Electron mec](#)
- [Equans](#)
- [PREVAIL](#)
- [Hprobe Myconic](#)
- [SCREEN](#)
- [FAMES Pilote Line](#)
- [Keysom](#)
- [Keysight](#)
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- [innodys](#)
- [Rigaku](#)
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- [Accretech](#)

Sponsors from Around the World

Semiconductor Industry Giants and Regional Champions:

- **Platinum:** Soitec and Lam Research
- **Gold:** Siemens, Schneider Electric, Prevail, ARDIAN, Equans, ASML
- **Silver:** TEL, Synopsis, Weebit Nano, Ebara, Screen, STMicroelectronics
- **Bronze:** ThermoFisher Scientific, Technic, BM&A, BBM Groupe, EVG, FMC, KELTEN, Banque Populaire Auvergne Rhône Alpes, AGILEO Automation, Veeco, IBM, Canada's Semiconductor Council, ASM, Accretech, SUSS Electron mec, LYNRED, KLA, GlobalFoundries, Applied Materials, Supernova Invest and with support from La Région Auvergne-Rhône-Alpes, the Carnot Network, Grenoble Alpes Métropole, SEMI.

Strong Media Engagement

Partnering with Major Semiconductor and Tech Media Outlets Worldwide:

- [EE Times Europe](#)
- [Microwave Journal](#)
- [Design & Reuse](#)
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- [TimesTech.in](#)
- [Chip Scale Review](#)
- [Global Advance Packaging](#)
- [Industrial News](#)
- [IN Electronics & Design](#)
- [What's New in Electronics](#)
- [Semiconductor Packaging News](#)

From the micro to the macro, LID World Summit 2026 presents innovations that will advance chip competitiveness globally by strengthening industry capacity and supporting the quest for a better, healthier, and safer world.

Join us this June. Leave with confidence in the possible.



For more information:

[LID World Summit website](#)

[CEA-Leti on LinkedIn](#)

CEA-Leti Press Contact

Agency

Sarah-Lyle Dampoux

sldampoux@mahoneylyle.com

+33 6 74 93 23 47